



## The ExaNeSt HPC project: Storage, Interconnect, Cooling

- **Storage**: fast, distributed in-node non-volatile memory
- **Interconnect**: low-latency, unified compute & storage traffic
- **Packaging**: advanced, liquid-cooled
- **App's**: real, scientific and datacenter
- **Prototype**: 1000+ ARM cores
- from EuroServer: ARM nodes with UNIMEM address space & shared I/O
- from ExaNoDe: Chiplets, Si Interposer
- with ECOSCALE: Heterog. ARM+FPGA's



Iceotope Ltd:  
*Fully Immersed  
Cooling Technology*